Status Report for SI to TSG

Study Item Name: Improvement of Inter-frequency and inter-system measurement for 1.28Mcps TDD

SOURCE: Rapporteur   **TSG: RAN**   **WG: WG1**

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Ref. to SI sheet: RAN_Study_Items_after_RAN_16.doc

Progress Report since the last TSG (for all involved WGs):

RAN1: RAN1 is the leading working group of this SI. The purpose of this SI is firstly to evaluate and quantify some possible problems from current inter-frequency and inter-system measurement for 1.28Mcps TDD and then propose some set of solutions in order to resolve them, particularly in terms of enlarging the measurement window and avoiding the possible measurement failures. In the RAN #27 meeting, the description of two study areas was agreed in principle [11][12], and updated clean version of this TR [13] was submitted in RAN 1 #28 meeting for final official approval. However, it was not treated in RAN1 #28 meeting due to the lack of time, but finally approved via e-mail reflector. Other related two contributions [14][15] which includes the simulation results and corresponding text proposal for the proposed methods were also submitted, but they were also not presented. . Hence, they will be treated in the next RAN1 #29 meeting.

RAN2: There is no progress since the last TSG RAN meeting.

RAN3: Internal skeleton TR [16] "Improvement of inter-frequency and inter-system measurements for 1.28 Mcps TDD" was approved in principle in RAN3 #30 meeting and finally noted in RAN3 #31meeting.

RAN4: There is no need of further progress.

List of Completed elements (for complex work items):

RAN1: Agreement on the study areas of the SI.

RAN2: Clarification of the SI.

RAN3: Completion of internal skeleton TR for signalling support.

RAN4: Agreement on the impact to the WG4 related specifications

List of open issues:

-   Performance evaluation and simulation for the asymmetric time slot allocation pattern to all the possible scenarios, necessary upper layer signaling and its impact on DCA, power control, beam-forming and uplink synchronization function.

-   Performance evaluation and simulation for the combination of different time slot allocation pattern, necessary upper layer signaling and its impact on DCA, power control, beam-forming and uplink synchronization function.

-   Improved signalling support for the specific measurement scheme.

Estimates of the level of completion (when possible):

20 %

SI completion date review:

TSG RAN #19 (March 2003)

References to WG's internal documentation and/or TRs:

[1]   3GPP TSGR1-02-0516: "Revised draft TR 25.888 on Improvement of Inter-frequency and inter-system measurement for 1.28Mcps TDD   (revision of R1-02-0468)"

[2]   3GPP TSGR1-02-0663: "Improvement of monitoring GSM from 1.28Mcps TDD"

[3]   3GPP TSGR1-02-0664: "Improvement of monitoring FDD from 1.28Mcps TDD"

[4]   3GPP TSGR1-02-0665: "Improvement of monitoring 3.84Mcps TDD from 1.28Mcps TDD"

[5]   3GPP TSGR1-02-0666: "Improvement of monitoring 1.28Mcps TDD from 1.28Mcps TDD"

[6]   3GPP TSGR1-02-0780: "Inter-RAT/Frequency study overview : asymmetric pattern for time slot allocation"

[7]   3GPP TSGR1-02-0781: "Inter-RAT/Frequency study overview : Combination of different time slot allocation pattern"

[8]   3GPP TSGR3-020256, "Skeleton TR3-011 v001", Samsung Electronics, April. 2002

[9]   3GPP TSGR3-020981, "Signalling support for improvement of inter-RAT measurements", Samsung Electronics, April. 2002

[10]   3GPP TSGR3-021595, "Skeleton TR3-011 v001", Samsung Electronics, May. 2002

[11]   3GPP TSGR1-02-1000, Inter-system/Frequency study overview: asymmetric pattern for time slot allocation (Revision of R1-02-0874), Samsung Electronics, July. 2002

[12]   3GPP TSGR1-02-1001, Inter-system/Frequency study overview: Combination of different time slot allocation pattern (Revision of R1-02-0875), Samsung Electronics, July. 2002

[13]   3GPP TSGR1-02-1059, Updated TDD inter-RAT measurement TR 25.888, Samsung Electronics, Aug. 2002

[14]   3GPP TSGR1-02-1060, Comparison of asymmetric pattern and conventional scheme used for different measurement purpose, Samsung Electronics, Aug. 2002

[15]   3GPP TSGR1-02-1125, Comparison of pattern combination scheme and conventional scheme used for different measurement purpose, Samsung Electronics, Aug. 2002

[16]   3GPP TSG R3-022092 TR R3-011 Improvement of inter-frequency and inter-system measurements for 1.28Mcps TDD, Samsung Electronics, Aug. 2002.